

MECHANICAL CASE OUTLINE

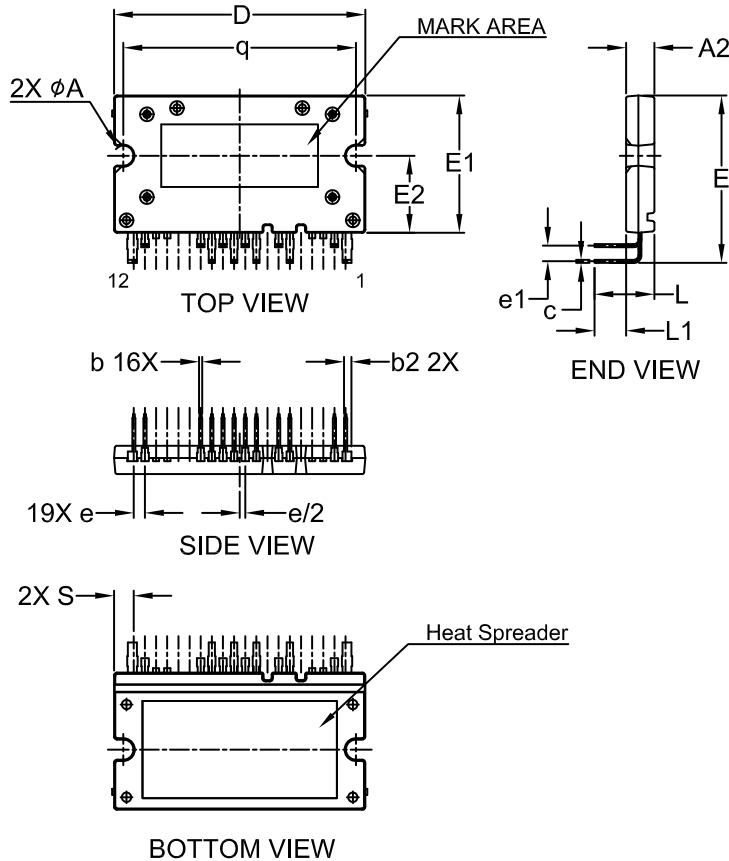
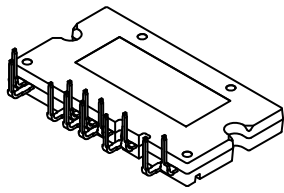
PACKAGE DIMENSIONS



APMCD-B16 / 12LD, AUTOMOTIVE MODULE

CASE MODGK
ISSUE C

DATE 03 NOV 2020

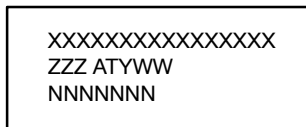


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A2	4.30	4.50	4.70
b	0.45	0.50	0.60
b2	1.15	1.20	1.30
c	0.45	0.50	0.60
D	39.90	40.10	40.30
E	26.20	26.70	27.20
E1	21.70	21.90	22.10
E2	12.10	12.30	12.50
e	1.478	1.778	2.078
e1	2.20	2.50	2.80
L	9.20	9.55	9.90
L1	4.70	5.05	5.40
q	36.85	37.10	37.35
S	3.159 REF		
ϕA	2.95	3.20	3.45

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
 ZZZ = Lot ID
 AT = Assembly & Test Location
 Y = Year
 W = Work Week
 NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	APMCD-B16 / 12LD, AUTOMOTIVE MODULE	PAGE 1 OF 1

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